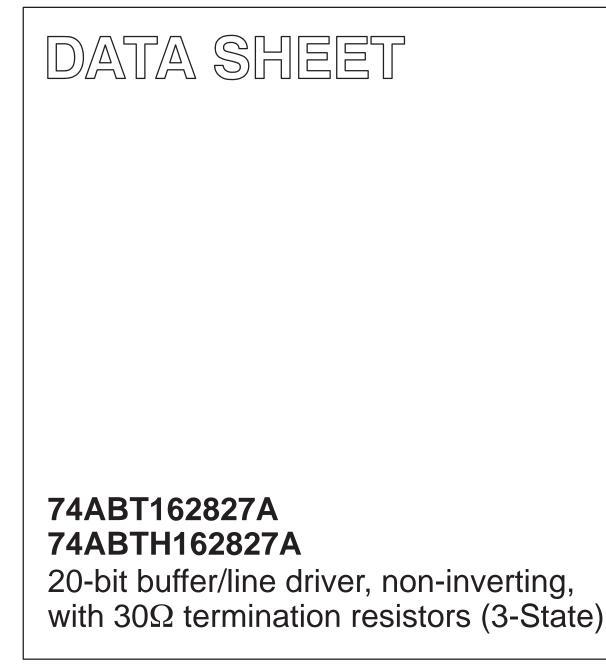
INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Feb 26 IC23 Data Handbook

1998 Feb 27





UNIT

ns

pF pF μA mA

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

74ABT162827A 74ABTH162827A

FEATURES

- \bullet Multiple V_{CC} and GND pins minimize switching noise
- Live insertion/extraction permitted
- 3-State output buffers
- Power-up 3-State
- 74ABTH162827A incorporates bus-hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Output capability: +64mA/-32mA

QUICK REFERENCE DATA

- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

DESCRIPTION

The 74ABT162827A high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT162827A 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NOR Output Enables (n $\overline{OE1}$, n $\overline{OE2}$) for maximum control flexibility.

The 74ABT162827A is designed with 30Ω series resistance in both the pull–up and pull–down output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

Two options are available, 74ABT162827A which does not have the bus-hold feature and 74ABTH162827A which incorporates the bus-hold feature.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C; GND = 0V	TYPICAL	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	$C_L = 50 pF; V_{CC} = 5V$	1.8 1.9	
C _{IN}	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	4	
C _{OUT}	Output capacitance	$V_{O} = 0V \text{ or } V_{CC}; 3\text{-State}$	6	
I _{CCZ}	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5V$	500	
I _{CCL}	Quescent supply cullent	Outputs Low; $V_{CC} = 5.5V$	9	

ORDERING INFORMATION

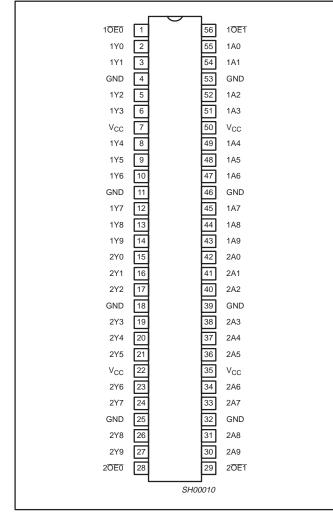
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT162827A DL	BT162827A DL	SOT371-1
56-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABT162827A DGG	BT162827A DGG	SOT364-1
56-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH162827A DL	BH162827A DL	SOT371-1
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH162827A DGG	BH162827A DGG	SOT364-1

PIN DESCRIPTION

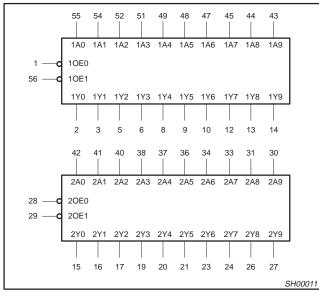
PIN NUMBER	SYMBOL	FUNCTION		
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 - 1A9 2A0 - 2A9	Data inputs		
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 - 1Y9 2Y0 - 2Y9	Data outputs		
1, 56, 28, 29	10E0, 10E1 20E0, 20E1	Output enable inputs (active-Low)		
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)		
7, 22, 35, 50	V _{CC}	Positive supply voltage		

74ABT162827A 74ABTH162827A

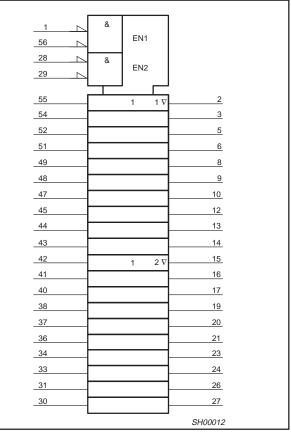
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



FUNCTION TABLE

INPL	JTS	OUTPUTS	OPERATING MODE
nOEx	nAx	nYx	
L	L	L	Transparent
L	Н	Н	Transparent
Н	Х	Z	High impedance

X = Don't care

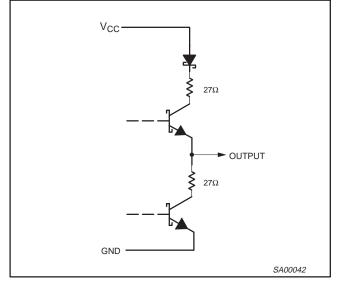
Z = High impedance "off" state

H = High voltage level

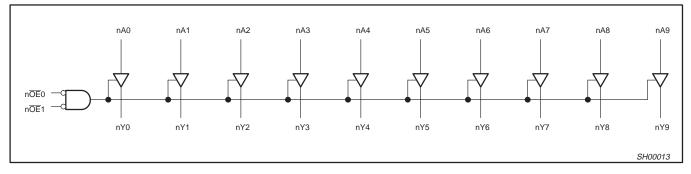
L = Low voltage level

74ABT162827A 74ABTH162827A

SCHEMATIC OF Y OUTPUTS



LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
Ι _{ΟΚ}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +5.5	V
1		Output in Low state	128	mA
IOUT	DC output current	Output in High state	-64	mA
T _{stg}	Storage temperature range		–65 to 150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

74ABT162827A 74ABTH162827A

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
		MIN	MAX	
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Low-level Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		12	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

		TEST CONDITIONS		LIMITS					
SYMBOL	PARAMETER			T _{amb} = +25°C			T _{amb} =	= -40°C 85°C	UNIT
				MIN	TYP	MAX	MIN	MAX	
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA			-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V; I_{OH} = -3mA; V_{I} = V$	_{IL} or V _{IH}	2.5	3.1		2.5		V
V _{OH}	High-level output voltage	V _{CC} = 5.0V; I _{OH} = -3mA; V _I = V	_{IL} or V _{IH}	3.0	3.6		3.0		V
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} = V$	V _{IL} or V _{IH}	2.0	2.7		2.0		V
M	Low-level output voltage	$V_{CC} = 4.5V; I_{OH} = 8mA; V_I = V_{II}$	_ or V _{IN}			0.65		0.65	V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5$ V; $I_{OL} = 12$ mA; $V_{I} = V$	ΪL			0.80		0.80	V
I _I	Input leakage current	$V_{CC} = 5.5V; V_{I} = GND \text{ or } 5.5V$			±0.01	±1.0		±1.0	μA
		$V_{CC} = 5.5V; V_{I} = 5.5V$			0.01	1		1	μA
lı	Input leakage current 74ABTH162827A	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or } GND$	Control pins		±0.01	±1		±1	μA
	74ABTH162827A	$V_{CC} = 5.5V; V_I = V_{CC}$	Data nine4		0.01	1		1	μA
		$V_{CC} = 5.5V; V_{I} = 0$	Data pins ⁴		-1	-3		-5	μA
	B 11 11	$V_{CC} = 4.5 V; V_{I} = 0.8 V$		35			35		
I _{HOLD}	Bus Hold current A inputs ⁵ 74ABTH162827A	$V_{CC} = 4.5V; V_I = 2.0V$		-75		-75		μΑ	
	I IN BITTOLOLIN	$V_{CC} = 5.5V; V_{I} = 0 \text{ to } 5.5V$		±800					
I _{OFF}	Power-off leakage current	$V_{CC} = 0.0V; V_{O} = 4.5V; V_{I} = 0V$	/ or 5.5V		±5.0	±100		±100	μA
I _{PU} /I _{PD}	Power-up/down 3-State output current ³	$V_{CC} = 2.1V$; $V_O = 0.5V$; $V_I = GI$ $V_{OE} = Don't care$	ND or V _{CC} ;		±5.0	±50		±50	μΑ
I _{OZH}	3-State output High current	$V_{CC} = 5.5 V$; $V_{O} = 2.7 V$; $V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μA
I _{OZL}	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.5V; V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μA
I _{CEX}	Output High leakage current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GND \text{ or } V_{CC}$			1.0	50		50	μΑ
Ι _Ο	Output current ¹	V _{CC} = 5.5V; V _O = 2.5V		-50	-70	-180	-50	-180	mA
I _{CCH}		$V_{CC} = 5.5V$; Outputs High, $V_{I} = V_{CC}$	GND or		0.5	1		1	mA
I _{CCL}	Quiescent supply current	$V_{CC} = 5.5V$; Outputs Low, $V_I = 0$	GND or V _{CC}		9	19		19	mA
I _{CCZ}		$V_{CC} = 5.5V$; Outputs 3-State; $V_I = GND \text{ or } V_{CC}$			0.5	1		1	mA
ΔI_{CC}	Additional supply current per input pin ²	$V_{CC} = 5.5V$; one input at 3.4V, other inputs at V_{CC} or GND			0.2	1		1	mA

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

2. This is the increase in supply current for each input at 3.4V.

4. Unused pins at V_{CC} or GND.

5. This is the bus hold overdrive current required to force the input to the opposite logic state.

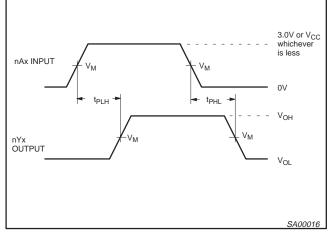
^{3.} This parameter is valid for any V_{CC} between 0V and 2.1V with a transition time of up to 10msec. From V_{CC} = 2.1V to V_{CC} = 5V \pm 10% a transition time of up to 100µsec is permitted.

74ABT162827A 74ABTH162827A

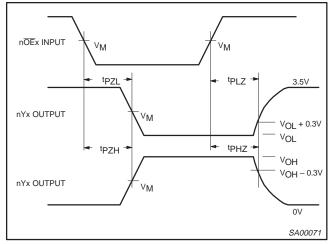
AC CHARACTERISTICS GND = 0V, $t_R = t_F = 2.5 \text{ns}, C_L = 50 \text{pF}, R_L = 500 \Omega$

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	I	∫ _{amb} = +25° V _{CC} = +5.0\		+8	= -40 to 5°C .0V ±0.5V	UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1.0 1.0	1.8 1.4	2.6 2.6	1.0 1.0	2.9 2.9	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.5 2.0	3.0 3.6	4.2 4.9	1.5 2.0	5.2 6.0	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	2.0 1.5	3.4 2.8	4.8 4.0	2.0 1.5	5.4 4.3	ns

AC WAVEFORMS



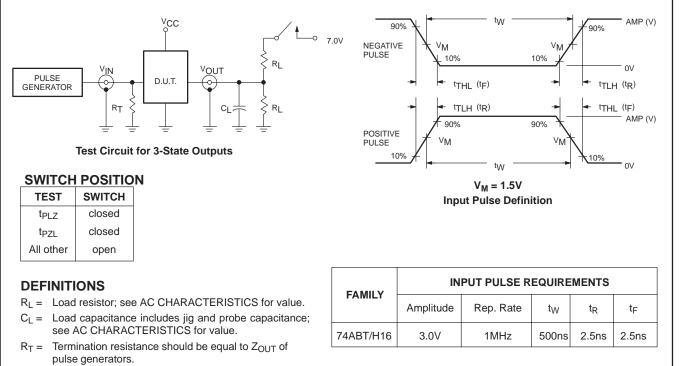
Waveform 1. Input (nAx) to Output (nYx) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

74ABT162827A 74ABTH162827A

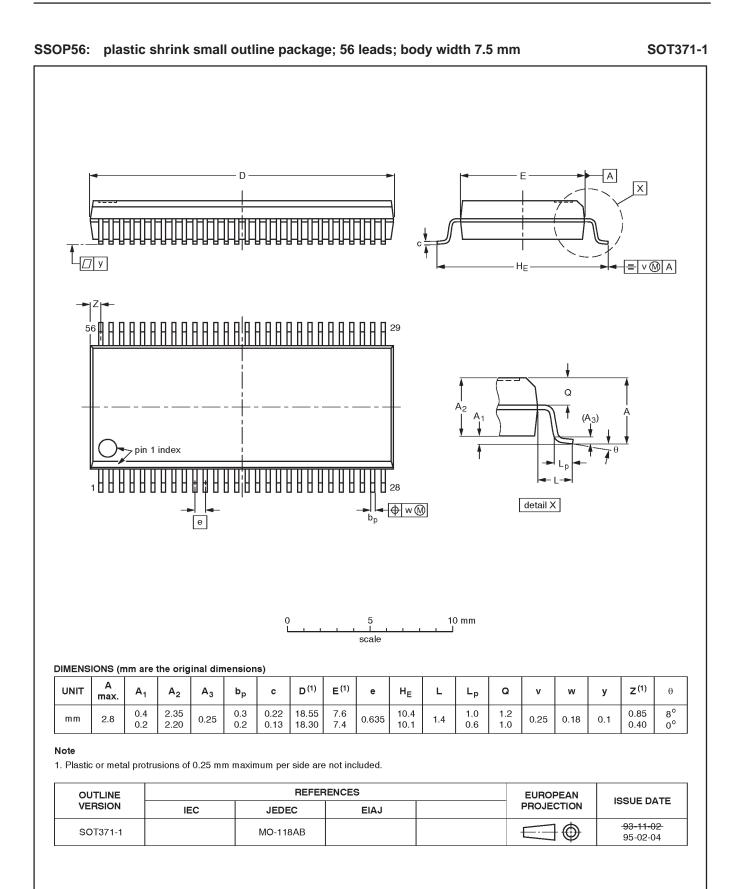
TEST CIRCUIT AND WAVEFORM



SA00018

20-bit buffer/line driver, non-inverting (3-State)

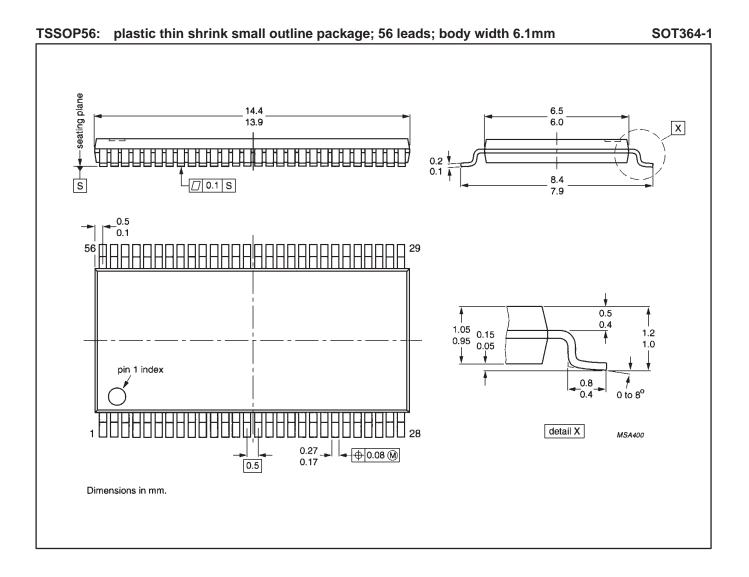
74ABT16827A 74ABTH16827A



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20-bit buffer/line driver, non-inverting (3-State)

74ABT16827A 74ABTH16827A



20-bit buffer/line driver, non-inverting (3-State)

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NOTES

74ABT162827A 74ABTH162827A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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